

3.5" NVMe Enclosure with Removable Module

THE 3.5" NVME ENCLOSURE WITH REMOVABLE SSD MODULE is for applications that require the frequent removal of SSD, fast transfer rates and large capacities.

It consists of two components; the 3.5" NVMe enclosure with PCIe Gen 3x4 interface that has standard 3.5" mounting holes and removable NVMe SSD module. The connectors between the drive module and the enclosure are rated for 100,000 mating cycles to support frequent insertions and removals.

The NVMe SSD module can use any COTS NVMe Solid State Drive (SSD), providing capacities up to 15TB and transfer rates of up to 7,877 MB/S. Options for FIPS140-2, FIPS197, TCG opal, and military erase secure.

- Capacities up to 16 TB
- 7,877 MB/S Transfer rates
- Removable SSD module
- PCIe Gen 3x4 interface
- 100,000 mating cycles
- 3.5" form factor
- Boot and/or disk storage
- COTS NVMe SSDs
- Military erase options
- FIPS140-2, FIPS197, TCG Opal options
- Option for thumbscrews to remove drive module without tools
- VxWorks, Linux and



EASILY REMOVE SSD DRIVE MODULE



(480)-483-3777

Ordering Information

3.5" NVMe Enclosure

	RRT-35NVMe-R-UR - X
Options May be left blank	
UR Polyurethane AR Acrylic	
Extended Temperature Range X -40°C to 85°C	ORDER EXAMPLES
	RRT-35-NVMe-R RRT-35-NVMe-R-UR-X

Removable NVMe SSD Drive Module RRT-DM-NVME- pSLC - 4TB - UR - X FE - TS -<u>Requirements</u> Options May be left blank NAND Flash Type No Tools TLC **3D NAND** TS Thumbscrews MLC Multi Level Cell pSLC Pseudo Single Level Cell Security FE Fast Erase Capacity SE1 NSA/CSS Manual 9-12 500GB - 15.3TB For TLC Erase 500GB - 8TB For TLC-X SE2 RCC-TG IRIG 106-107 1TB - 16TB For MLC Chapter 10 Erase 1TB - 8TB For pSLC OPAL TCG Opal Compliant SSD FIPS140-2 FIPS 140-2 Compliant SSD FIPS197 FIPS 197 Compliant SSD ORDER EXAMPLES Extended Temperature Range Х -40°C to 85°C RRT-DM-NVMe-TLC-15.3TB-TS RRT-DM-NVMe-TLC-3840GB-UR-X-SE1 **Conformal Coating** RRT-DM-NVMe-MLC-16TB-FIPS197 UR Polyurethane RRT-DM-NVMe-pSLC-1TB-UR-X-SE1 AR Acrylic

(480)-483-3777 •

Product Specifications

3.5" NVME ENCLOSURE WITH REMOVABLE MODULE

	PERFO	RMANCE			
NAND FLASH TYPE	TLC	MLC	pSLC	TLC-X	
CAPACITIES ¹	Up to 15.3TB	Up to 16TB	Up to 4TB	Up to 8TB	
INTERFACE ²	PCle Gen 3/4 x4	PCIe Gen 2 x 4	·	PCIe Gen 3 x4	
THROUGHPUT - SUSTAINED	3500MB/S (Gen3), 5000MB/S (Gen4)	800 MB/S	1000 MB/S	1500MB/S	
	RELI	ABILITY			
MTBF - DRIVE	1 million hours		2 million hours		
MTBF - 3.5" ENCLOSURE ³	3 million hours				
DATA RETENTION	1 year		5 years	1 year	
ENDURANCE (100GB) TOTAL BYTES WRITTEN	70 TBW		250 TBW	70 TBW	
ENDURANCE RATING ⁴	5 years				
CARRIER/DRIVE MODULE MATING CYCLES	100,000 mating cycles				
	PO	WER			
VOLTAGE	12V +/- 5%, +5V +/-	5%			
WATTS (IDLE)	7 W 1.5 W				
WATTS (ACTIVE)	20 W	10 W			
	ENVIRO	NMENTAL			
OPERATING TEMP., VITA 47 CLASS⁵	0° C to 55° C		0° C to 60° C	See TLC	
EXT. OPERATING TEMP., VITA 47 CLASS ⁵	See TLC-X	Not available	-40°C to 85°C		
STORAGE TEMP.	-40°C to 85°C				
ALTITUDE	10,000 ft. (3,000 meters)		80,000 ft. (24,000 meters)		
RELATIVE HUMIDITY	5% to 95%		·		
SHOCK, VITA 47 CLASS ⁶	20g, 11 millisecond terminal sawtooth pulse		40g, 11 millisecond terminal sawtooth pulse		
VIBRATION, VITA 47 CLASS ⁷	0.04 g2/Hz, 5 Hz to 100 Hz		0.1 g2/Hz, 100 Hz to 1000 Hz		
	PHY	SICAL			
FORM FACTOR	3.5"				
WEIGHT	30 oz. (849g)				
	4 0" x 5 75" x 1 625	5"(101.6mm x 146.1)	mm x 41.3mm)		
PITCH	1 1.0 × 0.10 × 1.020				

(4) Based on JESD218 standard with 4KB random write workload

(5) Thermal qualification per MIL-STD-810F, Method 501 Procedure II, and MIL-STD-810F, Method 502, Procedure II

(6) Shock qualification per MIL-STD-810F, Method 516, Procedure I

(7) Vibration qualification per MIL-STD-810F, Method 514, Procedure I



Red Rock Technologies, Inc. reserves the right to modify, change or discontinue specific products within its product line at its own discretion. Red Rock Technologies, Inc. does not assume any liability resulting from the application or use of its products. The information contained herein has been checked and is believed to be entirely accurate; however, no responsibility is assumed for inaccuracies. "Red Rock Technologies" and the mountain logo are registered trademarks of Red Rock Technologies, Inc. © Copyright 2023 Red Rock Technologies, Inc. All rights reserved. (Rev. 20230113a)